

PROCESS FOR MANUFACTURING SEMICONDUCTOR PACKAGE HAVING HOLLOW CHAMBER

ABSTRACT

A process for manufacturing a semiconductor package having a hollow chamber includes providing a bottom substrate having a bottom plate, a ring wall and a slot, wherein the ring wall and the bottom plate form the slot; forming an under ball metallurgy layer on a surface of the ring wall; bumping a plurality of solder balls on a surface of the under ball metallurgy layer, each of the solder balls comprises a diameter, wherein a spacing is spaced apart between two adjacent solder balls; performing reflow soldering to the solder balls for making the solder balls melting and interconnecting to form a connection layer; connecting a top substrate to the bottom substrate, wherein the lot of the bottom substrate is sealed by the top substrate to form a hollow chamber used for accommodating an electronic device.

FIG. 8